

**Features**

- Glass Passivated Die Construction
- Low Forward Voltage Drop
- High Current Capability
- High Surge Current Capability
- Designed for Surface Mount Application
- Plastic Material—UL Flammability 94V-0

**Mechanical Data**

- Case:ABS, Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Case
- Mounting Position: Any
- Marking: Type Number



Package: ABS

**Major Ratings and Characteristics**

$I_O$	0.5 A
$V_{RRM}$	200V ~ 1000V
$I_{FSM}$	30 A
$I_R$	5 $\mu$ A
$V_F$	1.0 V
$T_j$ (max.)	150°C

■ Maximum Ratings & Thermal Characteristics ( $T_A=25^\circ\text{C}$ , unless otherwise noted)

Items	Symbol	ABS2	ABS4	ABS6	ABS8	ABS10	UNIT
Peak Repetitive Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{DC}$	200	400	600	800	1000	V
RMS Reverse Voltage	$V_{R(RMS)}$	140	280	420	560	700	
Average Rectified Output Current	$I_O$	0.5					A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load(JEDEC Method)	$I_{FSM}$	30					
Current Squared Time	$I^2t$	3.7					A <sup>2</sup> S
Thermal resistance from junction to lead <sup>(1)</sup>	$R_{\theta JL}$	25					°C/W
Thermal resistance from junction to ambient <sup>(1)</sup>	$R_{\theta JA}$	80					
Thermal resistance from junction to ambient <sup>(2)</sup>	$R_{\theta JA}$	62.5					
Operating junction temperature range	$T_J$	-55 to +150					°C
Storage temperature range	$T_{STG}$	-55 to +125					

Note 1 : Mounted on glass epoxy PC board with 1.3mm<sup>2</sup> solder pad.

Note 2 : Mounted on aluminum substrate PC board with 1.3mm<sup>2</sup> solder pad.

■ Electrical Characteristics ( $T_A=25^\circ\text{C}$ , unless otherwise noted)

Items	Test conditions	Symbol	Min	Typ	Max	UNIT
Instantaneous forward voltage per leg	$I_F=0.4\text{ A}$ <sup>(3)</sup>	$V_F$	--	--	1	V
Reverse current	$V_R=V_{DC}$	$I_R$	$T_J=25^\circ\text{C}$	--	5	$\mu$ A
			$T_J=100^\circ\text{C}$	--	500	

Note 3 : Pulse test: 300 $\mu$ s pulse width, 1% duty cycle.

Characteristic Curves ( $T_A=25^{\circ}\text{C}$  unless otherwise noted)

Fig.1: Output Current Derating Curve

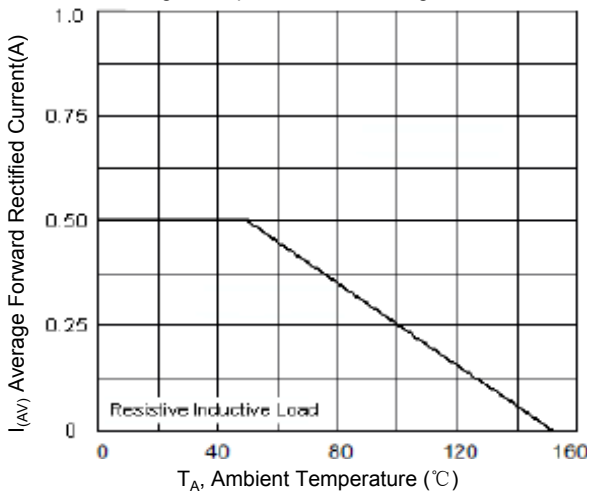


Fig.2: Typical Forward Characteristics (per leg)

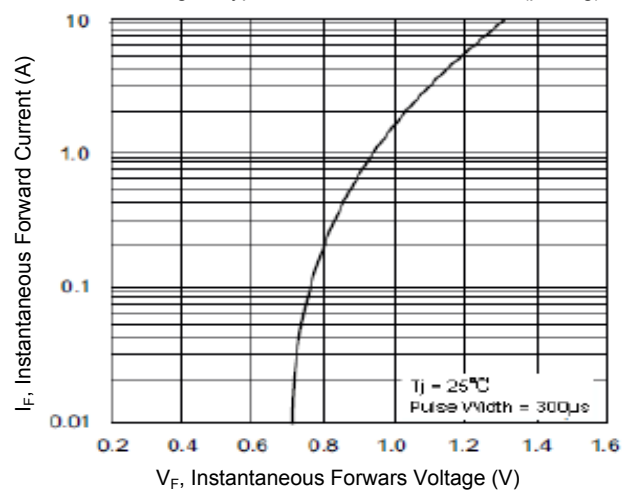


Fig.3: Max. Peak Forward Surge Current (per leg)

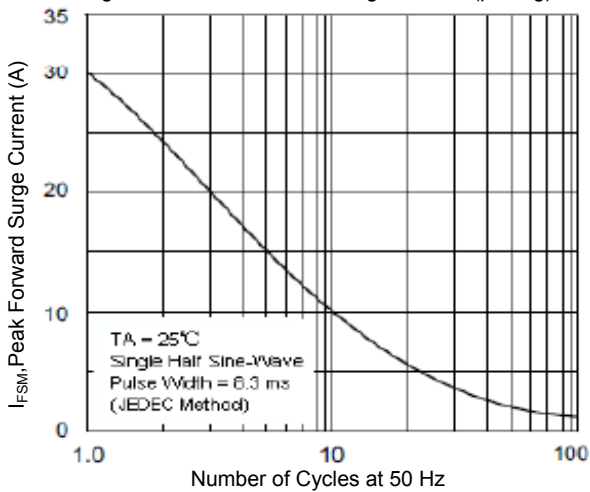


Fig.4: Typical Junction Capacitance

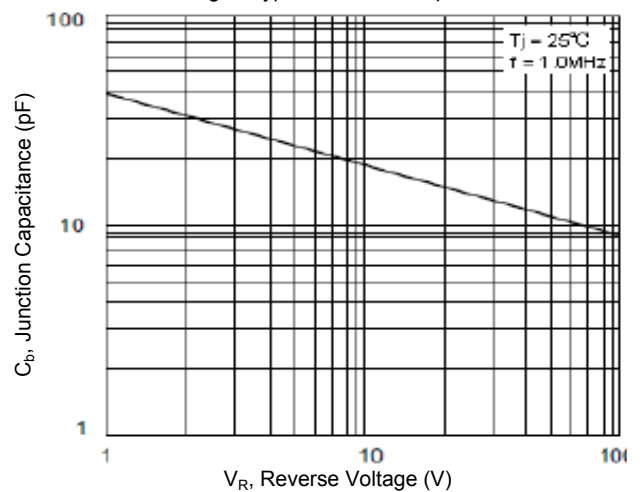
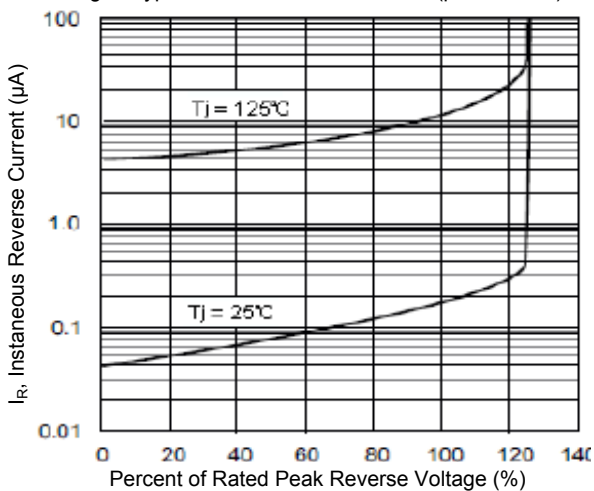
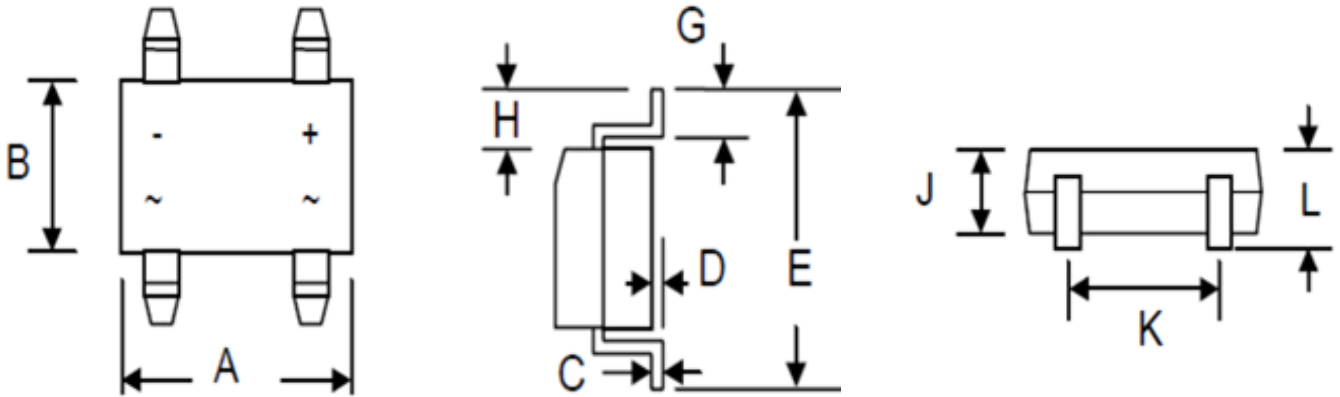


Fig.5: Typical Reverse Characteristics (per element)



## Package Outline

### ABS



UNIT: mm (inch)

DIM	MIN	MAX	DIM	MIN	MAX
A	4.90 (0.154)	5.30 (0.209)	G	0.30 (0.012)	0.80 (0.032)
B	4.30 (0.169)	4.80 (0.189)	H	0.80 (0.032)	1.20 (0.047)
C	0.15 (0.006)	0.25 (0.010)	J	1.20 (0.047)	1.40 (0.055)
D	0.05 (0.002)	0.15 (0.006)	K	3.80 (0.150)	4.20 (0.165)
E	6.00 (0.236)	6.40 (0.252)	L	--	1.50 (0.059)



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## 深圳市浩海电子有限公司

**SHENZHEN HAOHAI ELECTRONICS CO., LTD.**

2 floor(whole floor), BAOXIN Building. 0 Lane on the 8th. Yufeng Garden.  
82 District. BAOAN District, Shenzhen City, Guangdong Province, China.

中國 廣東省 深圳市 寶安區 82区 裕豐花園 零巷8號 寶馨樓 二楼(全层)

公司电话 TEL: +86-755-29955080、29955081、29955082、29955083  
总机八线 29955090、29955091、29955092、29955093

FAX: +86-755-27801767

E-mail: kkg@kkg.com.cn

<http://www.szhhe.com>

<http://www.kkg.com.cn>